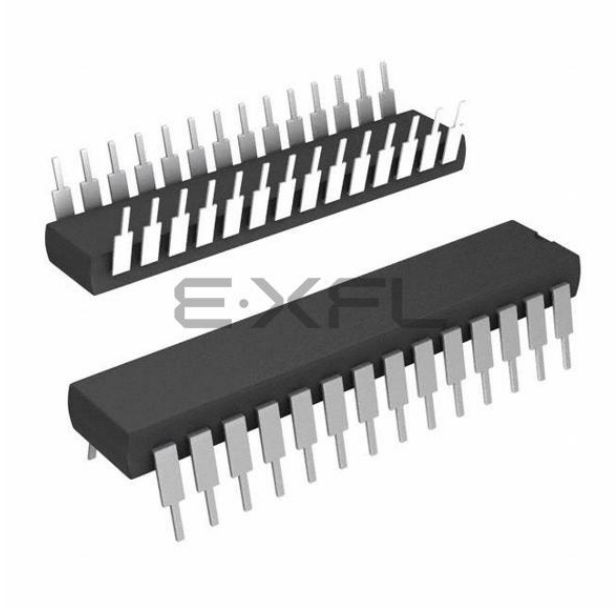
Microchip Technology - DSPIC33FJ16GS402-I/SP Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

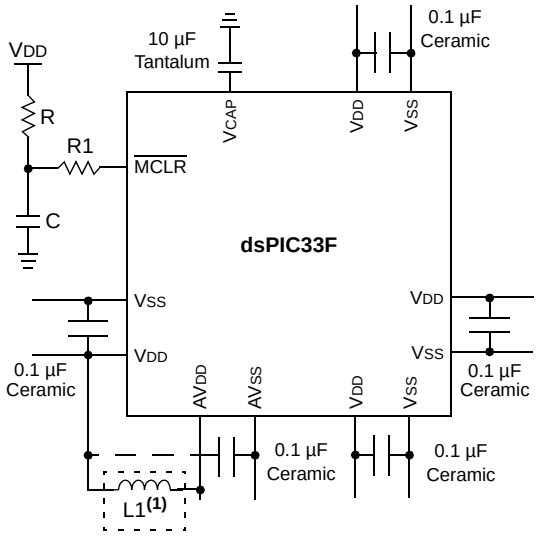
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gs402-i-sp

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	PPS Capable	Description
CMP1A	I	Analog	No	Comparator 1 Channel A.
CMP1B	I	Analog	No	Comparator 1 Channel B.
CMP1C	I	Analog	No	Comparator 1 Channel C.
CMP1D	I	Analog	No	Comparator 1 Channel D.
CMP2A	I	Analog	No	Comparator 2 Channel A.
CMP2B	I	Analog	No	Comparator 2 Channel B.
CMP2C	I	Analog	No	Comparator 2 Channel C.
CMP2D	I	Analog	No	Comparator 2 Channel D.
CMP3A	I	Analog	No	Comparator 3 Channel A.
CMP3B	I	Analog	No	Comparator 3 Channel B.
CMP3C	I	Analog	No	Comparator 3 Channel C.
CMP3D	I	Analog	No	Comparator 3 Channel D.
CMP4A	I	Analog	No	Comparator 4 Channel A.
CMP4B	I	Analog	No	Comparator 4 Channel B.
CMP4C	I	Analog	No	Comparator 4 Channel C.
CMP4D	I	Analog	No	Comparator 4 Channel D.
DACOUT	O	—	No	DAC output voltage.
ACMP1-ACMP4	O	—	Yes	DAC trigger to PWM module.
EXTREF	I	Analog	No	External voltage reference input for the reference DACs.
REFCLKO	O	—	Yes	REFCLKO output signal is a postscaled derivative of the system clock.
FLT1-FLT8	I	ST	Yes	Fault Inputs to PWM module.
SYNCI1-SYNCI2	I	ST	Yes	External synchronization signal to PWM master time base.
SYNCO1	O	—	Yes	PWM master time base for external device synchronization.
PWM1L	O	—	No	PWM1 low output.
PWM1H	O	—	No	PWM1 high output.
PWM2L	O	—	No	PWM2 low output.
PWM2H	O	—	No	PWM2 high output.
PWM3L	O	—	No	PWM3 low output.
PWM3H	O	—	No	PWM3 high output.
PWM4L	O	—	Yes	PWM4 low output.
PWM4H	O	—	Yes	PWM4 high output.
PGED1	I/O	ST	No	Data I/O pin for programming/debugging Communication Channel 1.
PGEC1	I	ST	No	Clock input pin for programming/debugging Communication Channel 1.
PGED2	I/O	ST	No	Data I/O pin for programming/debugging Communication Channel 2.
PGEC2	I	ST	No	Clock input pin for programming/debugging Communication Channel 2.
PGED3	I/O	ST	No	Data I/O pin for programming/debugging Communication Channel 3.
PGEC3	I	ST	No	Clock input pin for programming/debugging Communication Channel 3.
$\overline{MCLR}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AV_{DD}	P	P	No	Positive supply for analog modules. This pin must be connected at all times. AV_{DD} is connected to V_{DD}.
AV_{SS}	P	P	No	Ground reference for analog modules. AV_{SS} is connected to V_{SS}.
V_{DD}	P	—	No	Positive supply for peripheral logic and I/O pins.
V_{CAP}	P	—	No	CPU logic filter capacitor connection.
V_{SS}	P	—	No	Ground reference for logic and I/O pins.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; I = Input
ST = Schmitt Trigger input with CMOS levels; P = Power; O = Output
TTL = Transistor-Transistor Logic; PPS = Peripheral Pin Select

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

A low-ESR (<5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 24.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 21.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

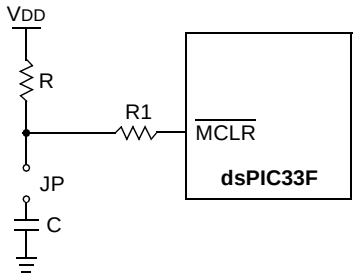
- Device Reset
- Device programming and debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor, C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

4.6.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program space without going through data space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit wide word address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

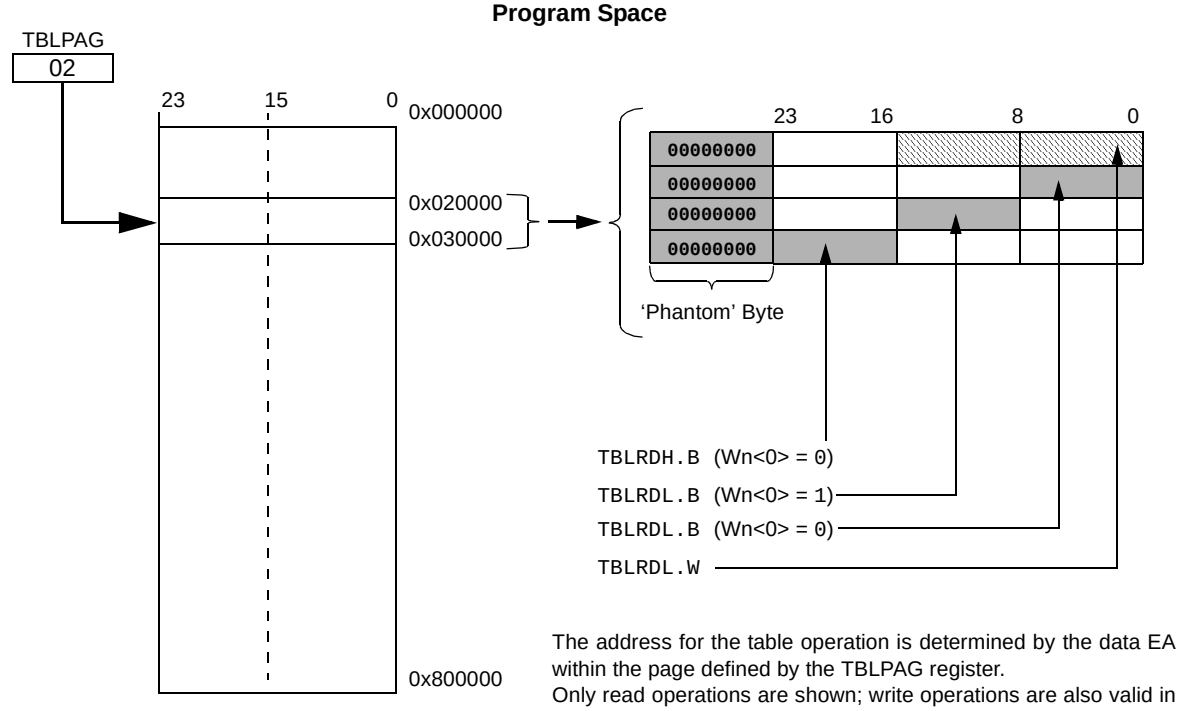
Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

- TBLRDL (Table Read Low):
  - In Word mode, this instruction maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).
  - In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.
- TBLRDH (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom byte', will always be '0'.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address, in the TBLRDL instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

Similarly, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

FIGURE 4-10: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



The address for the table operation is determined by the data EA within the page defined by the TBLPAG register.
Only read operations are shown; write operations are also valid in the user memory area.

4.6.3 READING DATA FROM PROGRAM MEMORY USING PROGRAM SPACE VISIBILITY

The upper 32 Kbytes of data space may optionally be mapped into any 16K word page of the program space. This option provides transparent access to stored constant data from the data space without the need to use special instructions (such as TBLRDL/H).

Program space access through the data space occurs if the Most Significant bit of the data space EA is '1' and Program Space Visibility (PSV) is enabled by setting the PSV bit in the Core Control register (CORCON<2>). The location of the program memory space to be mapped into the data space is determined by the Program Space Visibility Page register (PSVPAG). This 8-bit register defines any one of 256 possible pages of 16K words in program space. In effect, PSVPAG functions as the upper 8 bits of the program memory address, with the 15 bits of the EA functioning as the lower bits. By incrementing the PC by 2 for each program memory word, the lower 15 bits of data space addresses directly map to the lower 15 bits in the corresponding program space addresses.

Data reads to this area add a cycle to the instruction being executed, since two program memory fetches are required.

Although each data space address 8000h and higher maps directly into a corresponding program memory address (see Figure 4-11), only the lower 16 bits of the 24-bit program word are used to contain the data. The upper 8 bits of any program space location used as data should be programmed with '1111 1111' or '0000 0000' to force a NOP. This prevents possible issues should the area of code ever be accidentally executed.

Note:	PSV access is temporarily disabled during Table Reads/Writes.

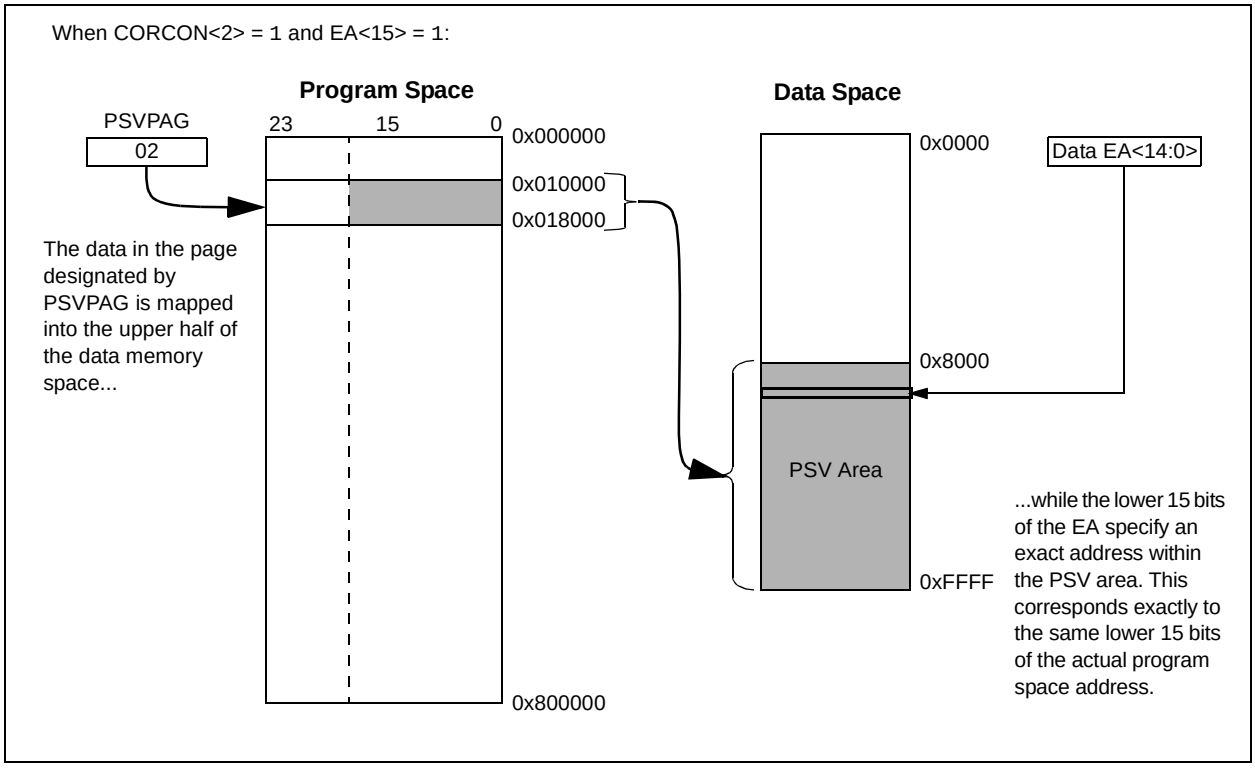
For operations that use PSV and are executed outside a REPEAT loop, the MOV and MOV.D instructions require one instruction cycle in addition to the specified execution time. All other instructions require two instruction cycles in addition to the specified execution time.

For operations that use PSV, and are executed inside a REPEAT loop, these instances require two instruction cycles in addition to the specified execution time of the instruction:

- Execution in the first iteration
- Execution in the last iteration
- Execution prior to exiting the loop due to an interrupt
- Execution upon re-entering the loop after an interrupt is serviced

Any other iteration of the REPEAT loop will allow the instruction using PSV to access data, to execute in a single cycle.

FIGURE 4-11: PROGRAM SPACE VISIBILITY OPERATION



REGISTER 7-17: IEC6: INTERRUPT ENABLE CONTROL REGISTER 6

R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
ADCP1IE	ADCP0IE	—	—	—	—	AC4IE	AC3IE
bit 15							bit 8

R/W-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
AC2IE	—	—	—	—	—	PWM4IE	PWM3IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ADCP1IE:** ADC Pair 1 Conversion Done Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 14 **ADCP0IE:** ADC Pair 0 Conversion Done Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 13-10 **Unimplemented:** Read as ‘0

bit 9 **AC4IE:** Analog Comparator 4 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 8 **AC3IE:** Analog Comparator 3 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 7 **AC2IE:** Analog Comparator 2 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 6-2 **Unimplemented:** Read as ‘0’

bit 1 **PWM4IE:** PWM4 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **PWM3IE:** PWM3 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

REGISTER 7-23: IPC4: INTERRUPT PRIORITY CONTROL REGISTER 4

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	CNIP2	CNIP1	CNIP0	—	AC1IP2	AC1IP1	AC1IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	MI2C1IP2	MI2C1IP1	MI2C1IP0	—	SI2C1IP2	SI2C1IP1	SI2C1IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **CNIP<2:0>:** Change Notification Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **AC1IP<2:0>:** Analog Comparator 1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **MI2C1IP<2:0>:** I2C1 Master Events Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **SI2C1IP<2:0>:** I2C1 Slave Events Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 8-5: ACLKCON: AUXILIARY CLOCK DIVISOR CONTROL REGISTER(1)

R/W-0	R-0	R/W-1	U-0	U-0	R/W-1	R/W-1	R/W-1
ENAPLL	APLLCK	SELACLK	—	—	APSTSCLR2	APSTSCLR1	APSTSCLR0
bit 15							bit 0

R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
ASRCSEL	FRCSEL	—	—	—	—	—	—
bit 7							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ENAPLL:** Auxiliary PLL Enable bit
1 = APLL is enabled
0 = APLL is disabled

bit 14 **APLLCK:** APLL Locked Status bit (read-only)
1 = Indicates that auxiliary PLL is in lock
0 = Indicates that auxiliary PLL is not in lock

bit 13 **SELACLK:** Select Auxiliary Clock Source for Auxiliary Clock Divider bit
1 = Auxiliary oscillators provides the source clock for auxiliary clock divider
0 = Primary PLL (FVCO) provides the source clock for auxiliary clock divider

bit 12-11 **Unimplemented:** Read as '0'

bit 10-8 **APSTSCLR<2:0>:** Auxiliary Clock Output Divider bits
111 = Divided by 1
110 = Divided by 2
101 = Divided by 4
100 = Divided by 8
011 = Divided by 16
010 = Divided by 32
001 = Divided by 64
000 = Divided by 256

bit 7 **ASRCSEL:** Select Reference Clock Source for Auxiliary Clock bit
1 = Primary oscillator is the clock source
0 = No clock input is selected

bit 6 **FRCSEL:** Select Reference Clock Source for Auxiliary PLL bit
1 = Select FRC clock for auxiliary PLL
0 = Input clock source is determined by ASRCSEL bit setting

bit 5-0 **Unimplemented:** Read as '0'

Note 1: This register is reset only on a Power-on Reset (POR).

9.2.2 IDLE MODE

The following occur in Idle mode:

- The CPU stops executing instructions
- The WDT is automatically cleared
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 9.4 "Peripheral Module Disable"**).
- If the WDT or FSCM is enabled, the LPRC also remains active

The device will wake-up from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the PWRSAV instruction, or the first instruction in the ISR.

9.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a PWRSAV instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

9.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this may not be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

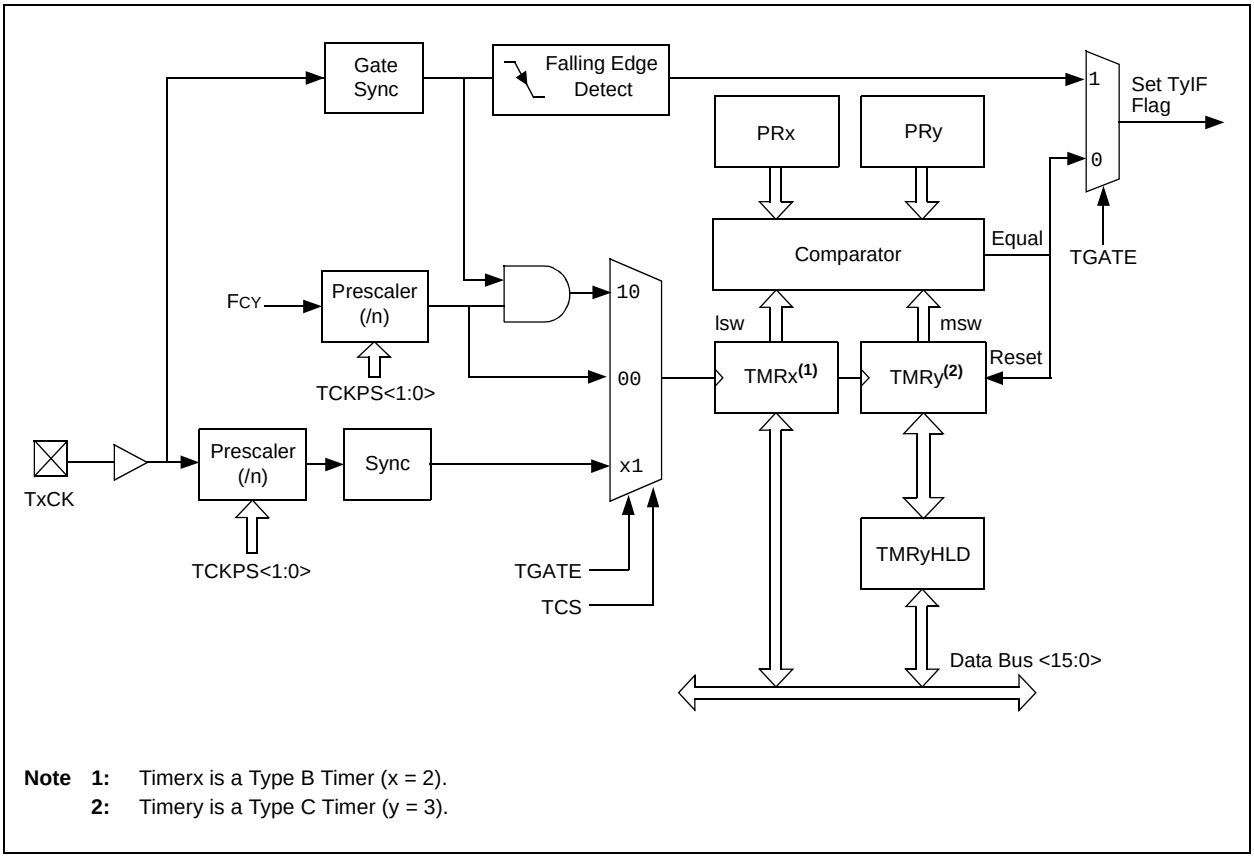
9.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers will have no effect and read values will be invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note:	If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

FIGURE 12-3: 32-BIT TIMER BLOCK DIAGRAM



Note 1: Timerx is a Type B Timer (x = 2).
2: Timery is a Type C Timer (y = 3).

15.2 Feature Description

The PWM module is designed for applications that require:

- High-resolution at high PWM frequencies
- The ability to drive Standard, Edge-Aligned, Center-Aligned Complementary mode, and Push-Pull mode outputs
- The ability to create multiphase PWM outputs

For Center-Aligned mode, the duty cycle, period phase and dead-time resolutions will be 8.32 ns.

Two common, medium power converter topologies are push-pull and half-bridge. These designs require the PWM output signal to be switched between alternate pins, as provided by the Push-Pull PWM mode.

Phase-shifted PWM describes the situation where each PWM generator provides outputs, but the phase relationship between the generator outputs is specifiable and changeable.

Multiphase PWM is often used to improve DC/DC Converter load transient response, and reduce the size of output filter capacitors and inductors. Multiple DC/DC Converters are often operated in parallel, but phase-shifted in time. A single PWM output operating at 250 kHz has a period of 4 μs, but an array of four PWM channels, staggered by 1 μs each, yields an effective switching frequency of 1 MHz. Multiphase PWM applications typically use a fixed-phase relationship.

Variable phase PWM is useful in Zero Voltage Transition (ZVT) power converters. Here, the PWM duty cycle is always 50%, and the power flow is controlled by varying the relative phase shift between the two PWM generators.

REGISTER 18-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)
- 1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by UEN<1:0>
- 0 = UARTx is disabled; all UARTx pins are controlled by port latches, UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** UARTx Stop in Idle Mode bit
- 1 = Discontinues module operation when device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)
- 1 = IrDA encoder and decoder are enabled
- 0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Enable bits
- 11 = UxTX, UxRX and BCLK pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLK pins are controlled by port latches

bit 7 **WAKE:** Wake-up on Start bit Detect During Sleep Mode Enable bit
- 1 = UARTx will continue to sample the UxRX pin; interrupt is generated on falling edge, bit is cleared in hardware on the following rising edge
- 0 = No wake-up is enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Enables Loopback mode
- 0 = Loopback mode is disabled

bit 5 **ABAUD:** Auto-Baud Enable bit
- 1 = Enable baud rate measurement on the next character – requires reception of a Sync field (55h) before other data; cleared in hardware upon completion
- 0 = Baud rate measurement is disabled or has completed

Note 1: Refer to **"UART"** (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.

2: This feature is only available for the 16x BRG mode (BRGH = 0).

TABLE 24-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Operating Current (IDD)(2)						
DC20d	55	70	mA	-40°C	3.3V	10 MIPS See **Note 2**
DC20a	55	70	mA	+25°C		
DC20b	55	70	mA	+85°C		
DC20c	55	70	mA	+125°C		
DC21d	68	85	mA	-40°C	3.3V	16 MIPS See **Note 2** and **Note 3**
DC21a	68	85	mA	+25°C		
DC21b	68	85	mA	+85°C		
DC21c	68	85	mA	+125°C		
DC22d	78	95	mA	-40°C	3.3V	20 MIPS See **Note 2** and **Note 3**
DC22a	78	95	mA	+25°C		
DC22b	78	95	mA	+85°C		
DC22c	78	95	mA	+125°C		
DC23d	88	110	mA	-40°C	3.3V	30 MIPS See **Note 2** and **Note 3**
DC23a	88	110	mA	+25°C		
DC23b	88	110	mA	+85°C		
DC23c	88	110	mA	+125°C		
DC24d	98	120	mA	-40°C	3.3V	40 MIPS See **Note 2**
DC24a	98	120	mA	+25°C		
DC24b	98	120	mA	+85°C		
DC24c	98	120	mA	+125°C		
DC25d	128	160	mA	-40°C	3.3V	40 MIPS See **Note 2**, except PWM is operating at maximum speed (PTCON2 = 0x0000)
DC25a	125	150	mA	+25°C		
DC25b	121	150	mA	+85°C		
DC25c	119	150	mA	+125°C		
DC26d	115	140	mA	-40°C	3.3V	40 MIPS See **Note 2**, except PWM is operating at 1/2 speed (PTCON2 = 0x0001)
DC26a	112	140	mA	+25°C		
DC26b	110	140	mA	+85°C		
DC26c	108	140	mA	+125°C		

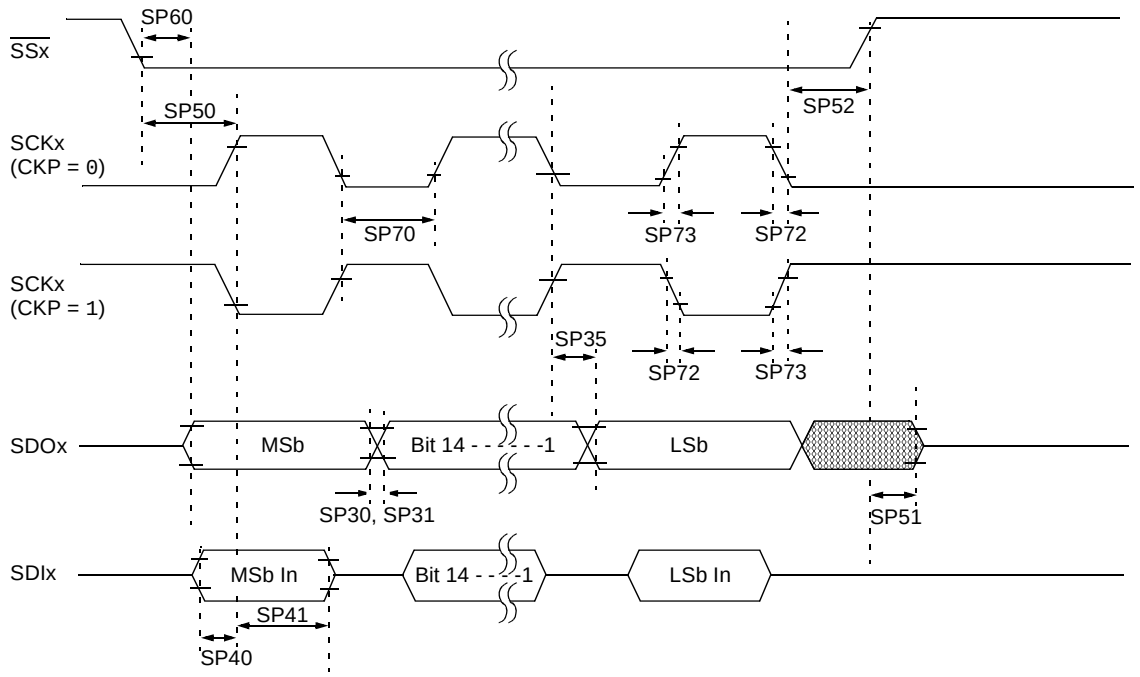
Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

2: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode with PLL, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU executing `while(1)` statement
- JTAG disabled

3: These parameters are characterized but not tested in manufacturing.

FIGURE 24-15: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 24-1 for load conditions.

TABLE 24-36: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

27.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 27-1: VOH – 4x DRIVER PINS

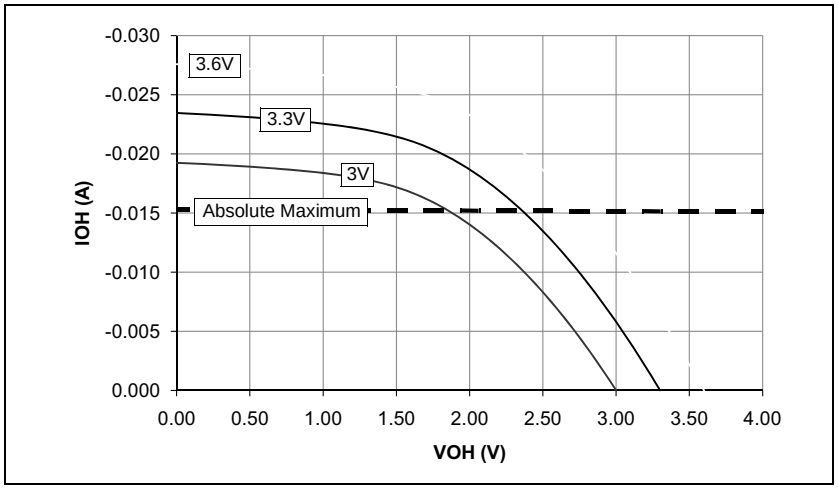


FIGURE 27-2: VOH – 8x DRIVER PINS

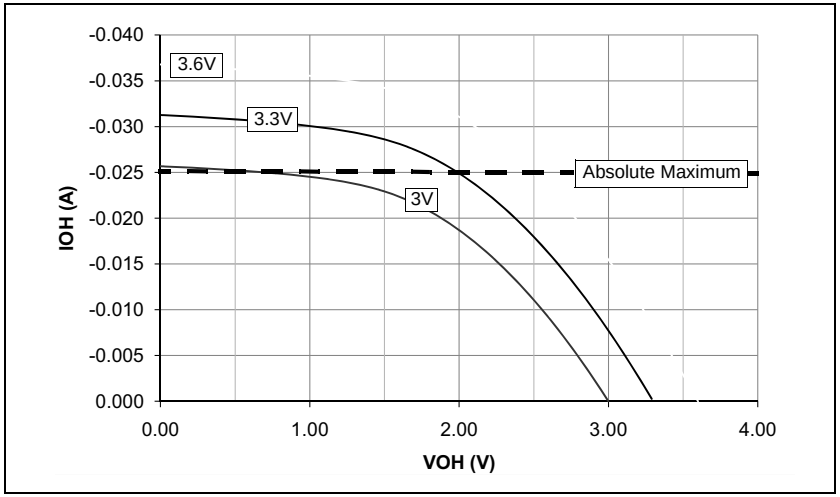


FIGURE 27-3: VOH – 16x DRIVER PINS

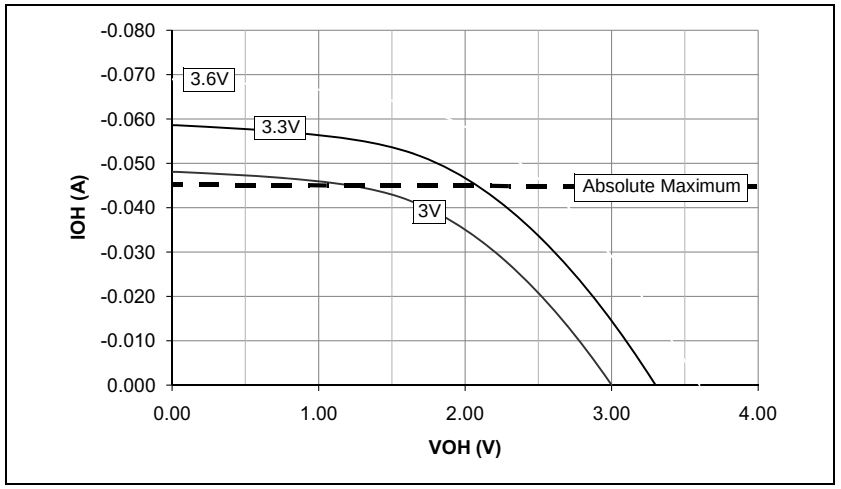


FIGURE 27-7: TYPICAL IPD CURRENT @ VDD = 3.3V

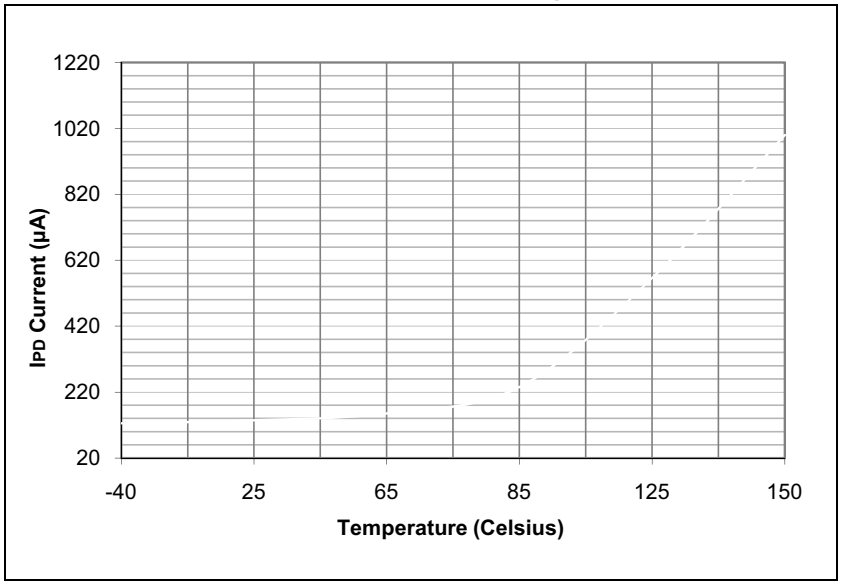


FIGURE 27-8: TYPICAL IDD CURRENT @ VDD = 3.3V

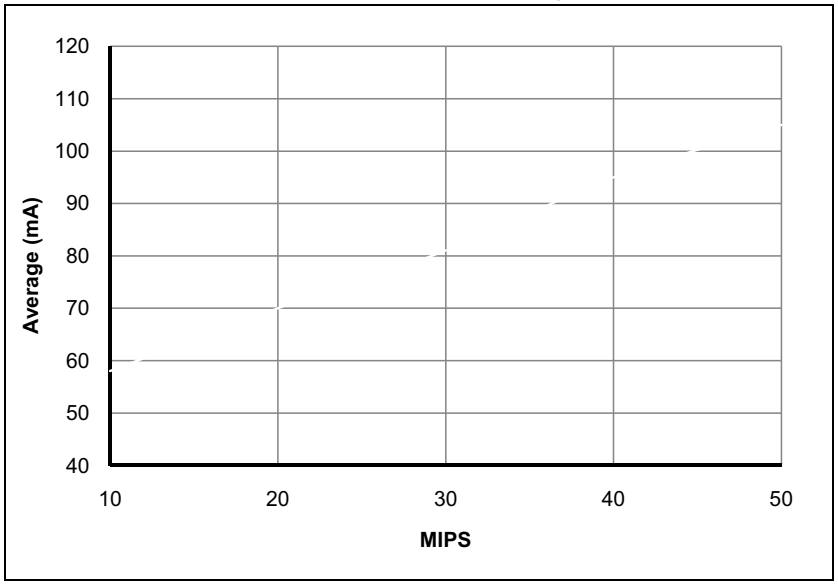


FIGURE 27-9: TYPICAL IDOZE CURRENT @ VDD = 3.3V

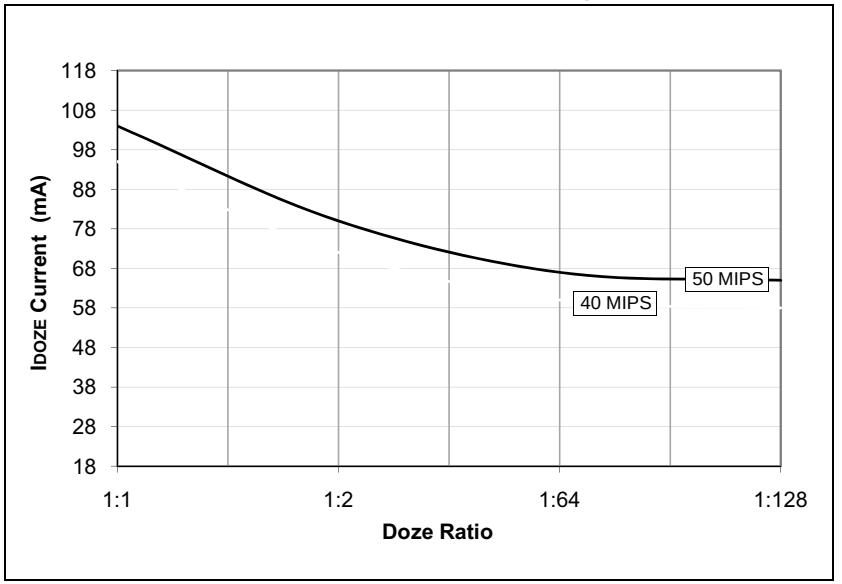
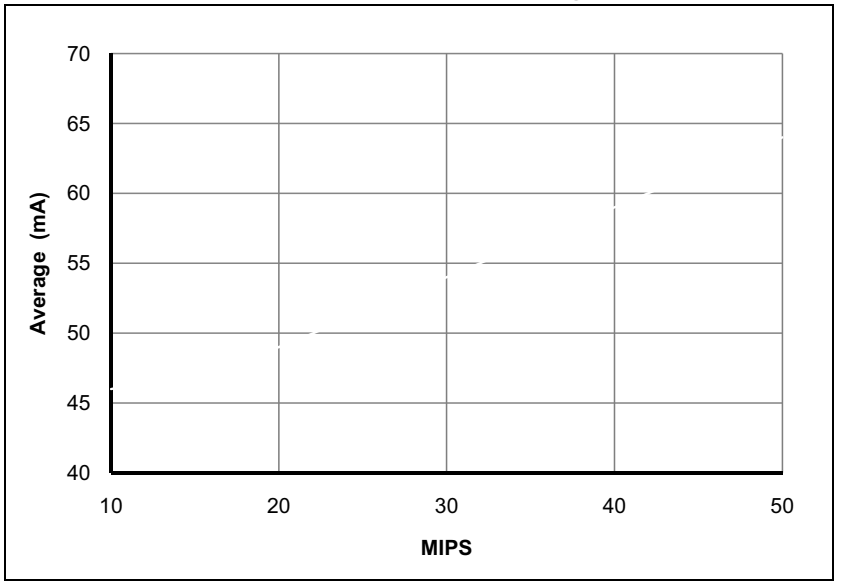
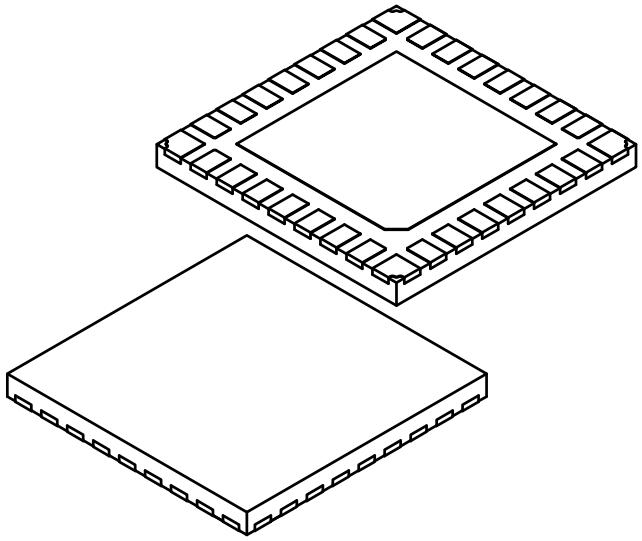


FIGURE 27-10: TYPICAL IIDLE CURRENT @ VDD = 3.3V



28-Lead Plastic Quad Flat, No Lead Package (MX) - 6x6x0.5mm Body [UQFN] Ultra-Thin with 0.40 x 0.60 mm Terminal Width/Length and Corner Anchors

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.40	0.50	0.60
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	(A3)		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2		4.00	
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2		4.00	
Terminal Width	b	0.35	0.40	0.45
Corner Pad	b2	0.25	0.40	0.45
Terminal Length	L	0.55	0.60	0.65
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
4. Outermost portions of corner structures may vary slightly.

Microchip Technology Drawing C04-0209B Sheet 2 of 2

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 8.0 "Oscillator Configuration"	Added Note 2 to the Oscillator System Diagram (see Figure 8-1). Added a paragraph regarding FRC accuracy at the end of **Section 8.1.1 "System Clock Sources"**. Added Note 1 and Note 2 to the OSCON register (see Register). Added Note 1 to the OSCTUN register (see Register 8-4). Added Note 3 to **Section 8.4.2 "Oscillator Switching Sequence"**.
Section 10.0 "I/O Ports"	Removed Table 9-1 and added reference to pin diagrams for I/O pin availability and functionality. Added paragraph on ADPCFG register default values to **Section 10.3 "Configuring Analog Port Pins"**. Added Note box regarding PPS functionality with input mapping to **Section 10.6.2.1 "Input Mapping"**.
Section 15.0 "High-Speed PWM"	Updated Note 2 in the PTCON register (see Register 15-1). Added Note 4 to the PWMCONx register (see Register 15-6). Updated Notes for the PHASEx and SPHASEx registers (see Register 15-9 and Register 15-10, respectively).
Section 16.0 "Serial Peripheral Interface (SPI)"	Added Note 2 and Note 3 to the SPIxCON1 register (see Register 16-2).
Section 18.0 "Universal Asynchronous Receiver Transmitter (UART)"	Updated the Notes in the UxMode register (see Register 18-1). Updated the UTXINV bit settings in the UxSTA register and added Note 1 (see Register 18-2).
Section 19.0 "High-Speed 10-bit Analog-to-Digital Converter (ADC)"	Updated the SLOWCLK and ADCS<2:0> bit settings and updated Note 1in the ADCON register (see Register 19-1). Removed all notes in the ADPCFG register and replaced them with a single note (see Register 19-4). Updated the SWTRGx bit settings in the ADCPCx registers (see Register 19-5, Register 19-6, Register 19-7, and Register 19-8).

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 24.0 "Electrical Characteristics"	Updated Typical values for Thermal Packaging Characteristics (see Table 24-3). Updated Min and Max values for Parameter DC12 (RAM Data Retention Voltage) and added Note 4 (see Table 24-4). Updated Characteristics for I/O Pin Input Specifications (see Table 24-9). Added ISOURCE to I/O Pin Output Specifications (see Table 24-10). Updated Program Memory values for Parameters 136, 137, and 138 (renamed to 136a, 137a, and 138a), added Parameters 136b, 137b, and 138b, and added Note 2 (see Table 24-12). Added Parameter OS42 (GM) to the External Clock Timing Requirements (see Table 24-16). Updated Conditions for symbol TPDLY (Tap Delay) and added symbol ACLK (PWM Input Clock) to the High-Speed PWM Module Timing Requirements (see Table 24-29). Updated Parameters AD01 and AD02 in the 10-bit High-Speed Analog-to-Digital Module Specifications (see Table 24-36). Updated Parameters AD50b, AD55b, and AD56b, and removed Parameters AD57b and AD60b from the 10-bit High-Speed Analog-to-Digital Module Timing Requirements (see Table 24-37).

Revision F (January 2012)

All occurrences of VDDCORE have been removed throughout the document.

This revision also includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE A-4: MAJOR SECTION UPDATES

Section Name	Update Description
"16-Bit Digital Signal Controllers (up to 16-Kbyte Flash and up to 2-Kbyte SRAM) with High-Speed PWM, ADC and Comparators"	Added the VTLA package to the dsPIC33FJ16GS404 and dsPIC33FJ16GS504 devices (see **TABLE 1: "dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 Controller Families"**). Added the **"Referenced Sources"** section. The following updates were made to the **"Pin Diagrams"** section: • Added 5V tolerant pin shading to pins 24-26 in the 28-pin SPDIP, SOIC package for the dsPIC33FJ16GS402 • Updated pin 31 of the 44-pin QFN package for the dsPIC33FJ16GS404 • Added VTLA pin diagrams for the dsPIC33FJ16GS404 and dsPIC33FJ16GS504 devices
Section 1.0 "Device Overview"	Removed the Precision Band Gap Reference from the device block diagram (see Figure 1-1). Updated the Pinout I/O Descriptions for AVDD, and AVSS (see Table 1-1).
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the Minimum Recommended Connection (see Figure 2-1).
Section 8.0 "Oscillator Configuration"	Updated the Oscillator System Diagram (see Figure 8-1). Added auxiliary clock configuration restrictions in **Section 8.2 "Auxiliary Clock Generation"**. Updated or added notes regarding register reset on a POR (see Register 8-1 through Register 8-5).
Section 19.0 "High-Speed 10-bit Analog-to-Digital Converter (ADC)"	Added Note 2 to ADCON: Analog-to-Digital Control Register (see Register 19-1). Removed all notes from ADSTAT: Analog-to-Digital Status Register (see Register 19-2).
Section 20.0 "High-Speed Analog Comparator"	Updated the Comparator Module Block Diagram (see Figure 20-1).
Section 21.0 "Special Features"	Add a new paragraph at the beginning of **Section 21.1 "Configuration Bits"**. Added the RTSP Effect column to the dsPIC33F Configuration Bits Description table (see Table 21-2). Updated the Connections for the On-chip Voltage Regulator diagram (see Figure 21-1). Updated the first paragraph of **Section 21.7 "In-Circuit Debugger"**.